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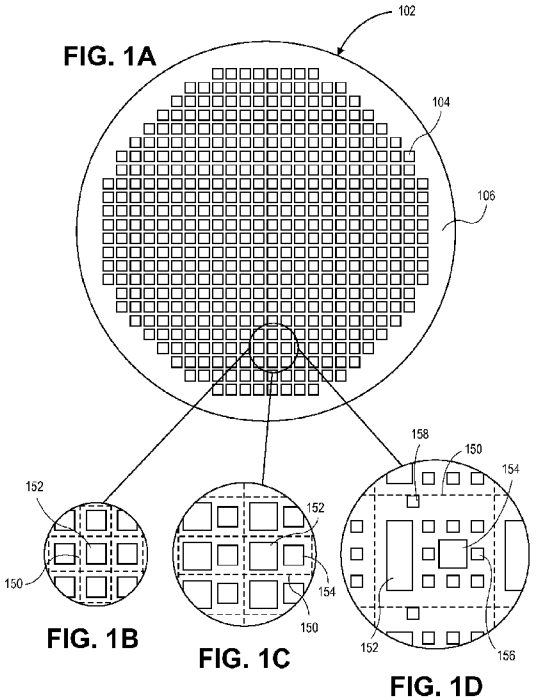
**Declarations under Rule 4.17**:

— *as to the identity of the inventor (Rule 4.17(i))*

*[Continued on next page]*

(54) **Title**: ADAPTIVE PATTERNING FOR PANELIZED PACKAGING

(57) **Abstract**: An adaptive patterning method and system for fabricating panel based package structures is described. Misalignment for individual device units in a panel or reticulated wafer may be adjusted for by measuring the position of each individual device unit and forming a unit-specific pattern over each of the respective device units.




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